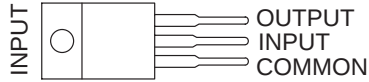
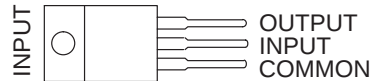


- 3-Terminal Regulators
- Output Current Up To 500 mA
- No External Components
- High Power-Dissipation Capability
- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation

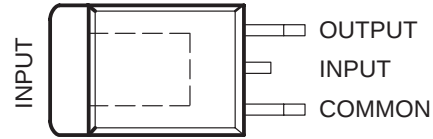
μA79M05 . . . KC (TO-220) PACKAGE
(TOP VIEW)



μA79M05 . . . KCS (TO-220) PACKAGE
(TOP VIEW)



μA79M05, μA79M08 . . . KTP PACKAGE
(TOP VIEW)



description/ordering information

This series of fixed-negative-voltage integrated-circuit voltage regulators is designed to complement the μA78M00 series in a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators delivers up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also as the power-pass element in precision regulators.

ORDERING INFORMATION

T_J	$V_{O(NOM)}$ (V)	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 125°C	–5	PowerFLEX™ (KTP)	Reel of 3000	μA79M05CKTPR	μA79M05C
		TO-220 (KC)	Tube of 50	μA79M05CKC	μA79M05C
		TO-220, short shoulder (KCS)	Tube of 20	μA79M05CKCS	
	–8	PowerFLEX (KTP)	Reel of 3000	μA79M08CKTPR	μA79M08C

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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recommended operating conditions

		MIN	MAX	UNIT
V_I Input voltage	μA79M05C	-7	-25	V
	μA79M08C	-10.5	-25	
I_O Output current			500	mA
T_J Operating virtual junction temperature		0	125	°C

electrical characteristics at specified virtual junction temperature, $V_I = -10$ V, $I_O = 350$ mA, $T_J = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	μA79M05C			UNIT
		MIN	TYP	MAX	
Output voltage	$V_I = -7$ V to -25 V, $I_O = 5$ mA to 350 mA	-4.8	-5	-5.2	V
	$T_J = 0^\circ\text{C}$ to 125°C	-4.75		-5.25	
Input voltage regulation	$V_I = -7$ V to -25 V		7	50	mV
	$V_I = -8$ V to -18 V		3	30	
Ripple rejection	$V_I = -8$ V to -18 V, $f = 120$ Hz, $I_O = 100$ mA, $T_J = 0^\circ\text{C}$ to 125°C	50			dB
	$I_O = 300$ mA	54	60		
Output voltage regulation	$I_O = 5$ mA to 500 mA		75	100	mV
	$I_O = 5$ mA to 350 mA		50		
Temperature coefficient of output voltage	$I_O = 5$ mA, $T_J = 0^\circ\text{C}$ to 125°C		-0.4		mV/°C
Output noise voltage	$f = 10$ Hz to 100 kHz		125		μV
Dropout voltage			1.1		V
Bias current			1	2	mA
Bias current change	$V_I = -8$ V to -18 V, $T_J = 0^\circ\text{C}$ to 125°C			0.4	mA
	$I_O = 5$ mA to 350 mA, $T_J = 0^\circ\text{C}$ to 125°C			0.4	
Short-circuit output current	$V_I = -30$ V		140		mA
Peak output current			0.65		A

† Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 2-μF capacitor across the input and a 1-μF capacitor across the output.

μA79M00 SERIES **NEGATIVE-VOLTAGE REGULATORS**

SLVS060K – JUNE 1976 – REVISED APRIL 2005

electrical characteristics at specified virtual junction temperature, $V_I = -19$ V, $I_O = 350$ mA, $T_J = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	μA79M08C			UNIT
		MIN	TYP	MAX	
Output voltage	$V_I = -10.5$ V to -25 V, $I_O = 5$ mA to 350 mA	-7.7	-8	-8.3	V
	$T_J = 0^\circ\text{C}$ to 125°C	-7.6		-8.4	
Input voltage regulation	$V_I = -10.5$ V to -25 V		8	80	mV
	$V_I = -11$ V to -21 V		4	50	
Ripple rejection	$V_I = -11.5$ V to -21.5 V, $f = 120$ Hz, $I_O = 100$ mA, $T_J = 0^\circ\text{C}$ to 125°C	50			dB
	$I_O = 300$ mA	54	59		
Output voltage regulation	$I_O = 5$ mA to 500 mA		90	160	mV
	$I_O = 5$ mA to 350 mA		60		
Temperature coefficient of output voltage	$I_O = 5$ mA, $T_J = 0^\circ\text{C}$ to 125°C		-0.6		mV/°C
Output noise voltage	$f = 10$ Hz to 100 kHz		200		μV
Dropout voltage	$I_O = 5$ mA		1.1		V
Bias current			1	2	mA
Bias current change	$V_I = -10.5$ V to -25 V, $T_J = 0^\circ\text{C}$ to 125°C			0.4	mA
	$I_O = 5$ mA to 350 mA, $T_J = 0^\circ\text{C}$ to 125°C			0.4	
Short-circuit output current	$V_I = -30$ V		140		mA
Peak output current			0.65		A

† Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 2-μF capacitor across the input and a 1-μF capacitor across the output.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
7704001HA	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI
UA79M05CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA79M05CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA79M05CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA79M05CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA79M05CKTPR	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA79M05CKTPRG3	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA79M05CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA79M05MUB	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI
UA79M08CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA79M08CKTPR	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA79M08CKTPRG3	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA79M08CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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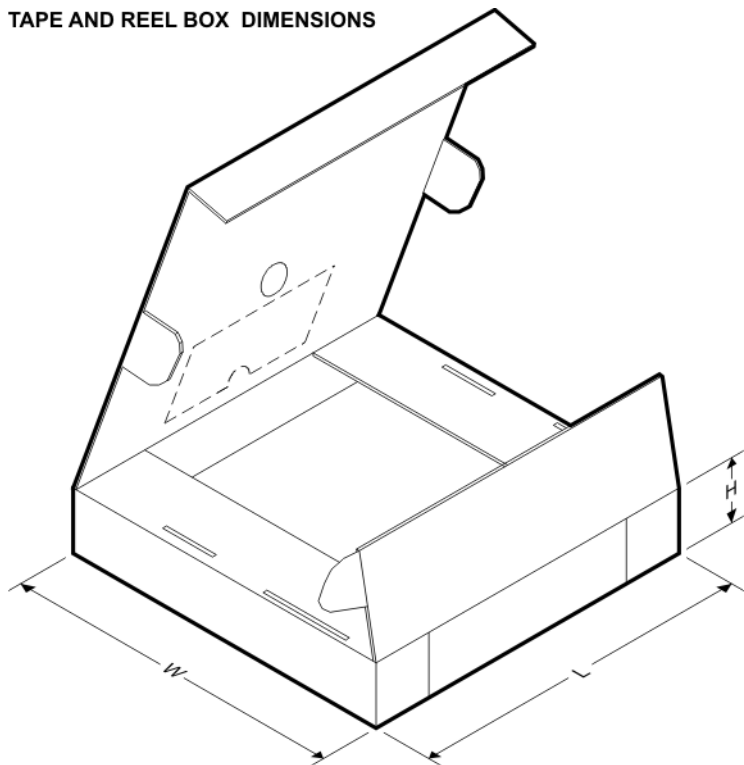
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA79M05CKVURG3	PFM	KVU	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
UA79M08CKVURG3	PFM	KVU	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS

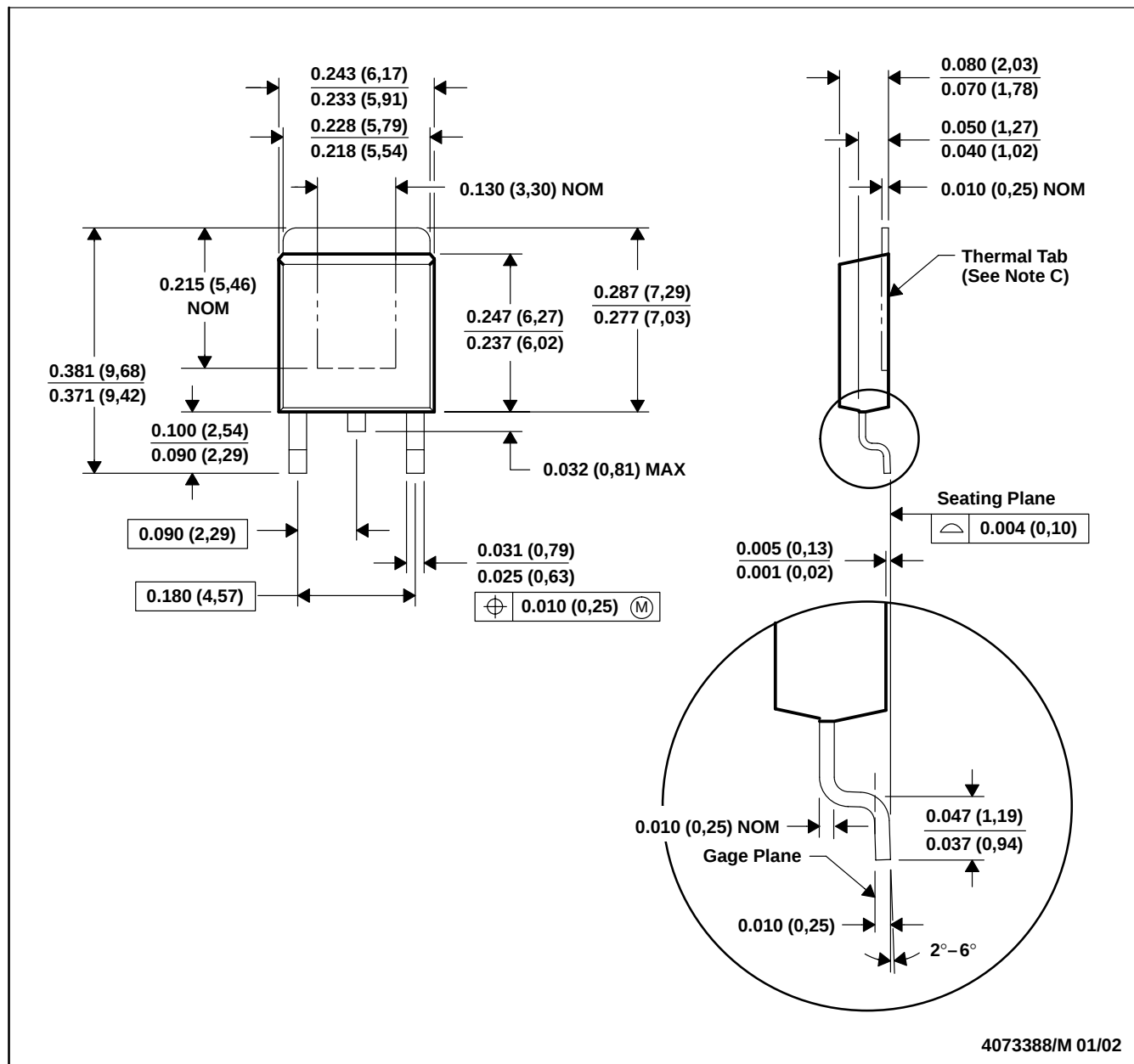


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA79M05CKVURG3	PFM	KVU	3	2500	340.0	340.0	38.0
UA79M08CKVURG3	PFM	KVU	3	2500	340.0	340.0	38.0

KTP (R-PSFM-G2)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE

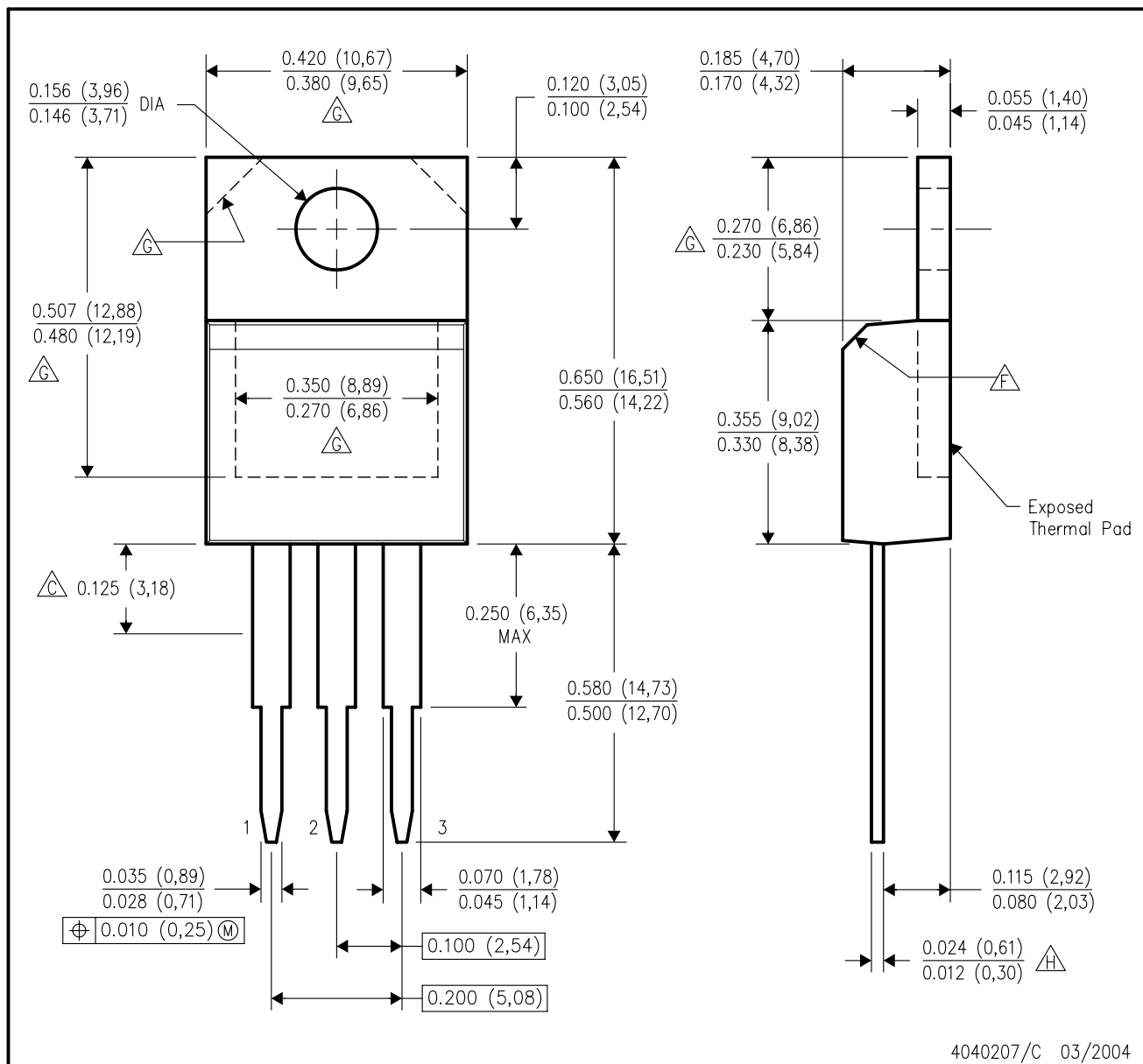


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - The center lead is in electrical contact with the thermal tab.
 - Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
 - Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.

KC (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE

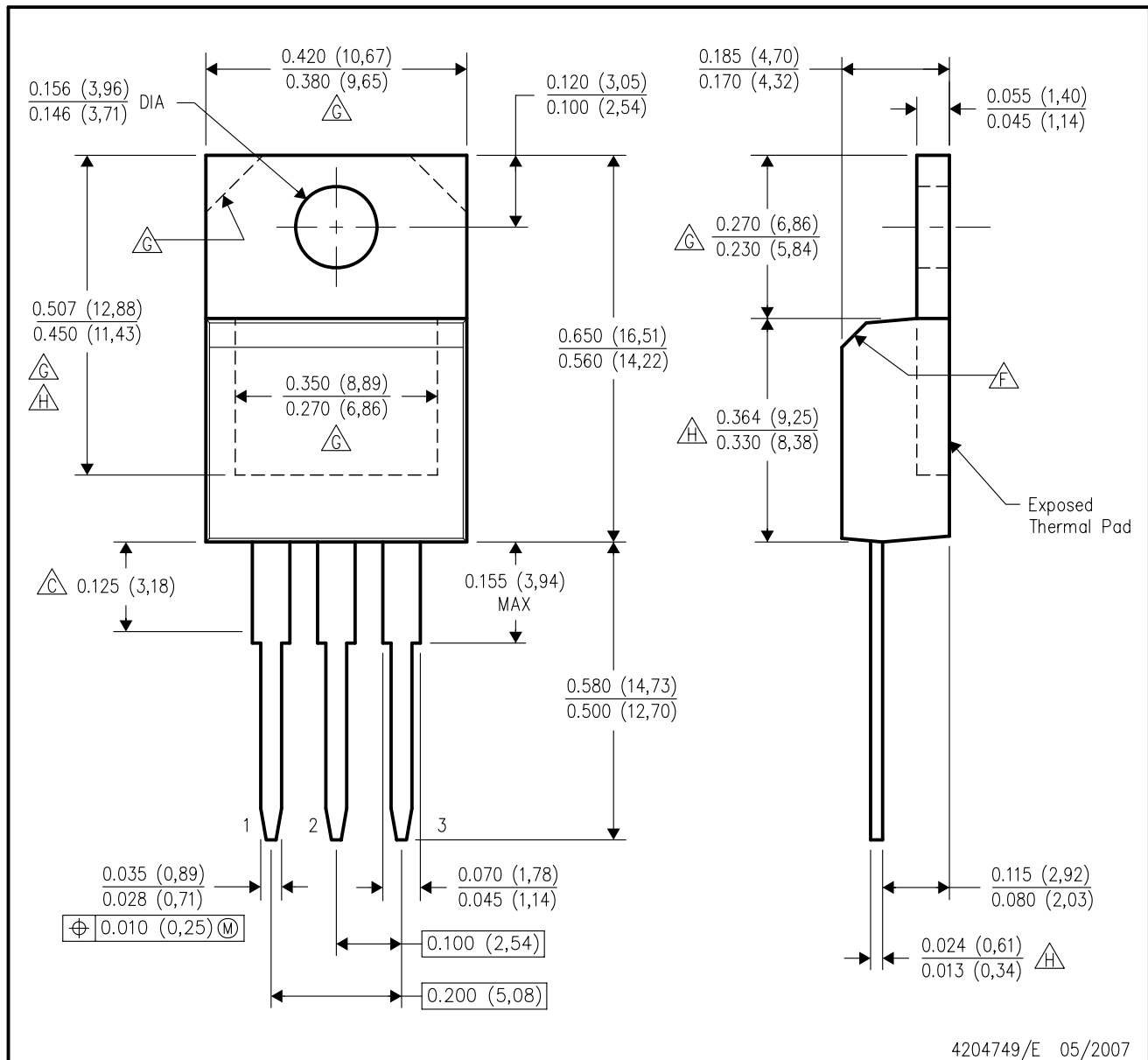


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- F. The chamfer is optional.
- G. Thermal pad contour optional within these dimensions.
- H. Falls within JEDEC TO-220 variation AB, except minimum lead thickness.

KCS (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



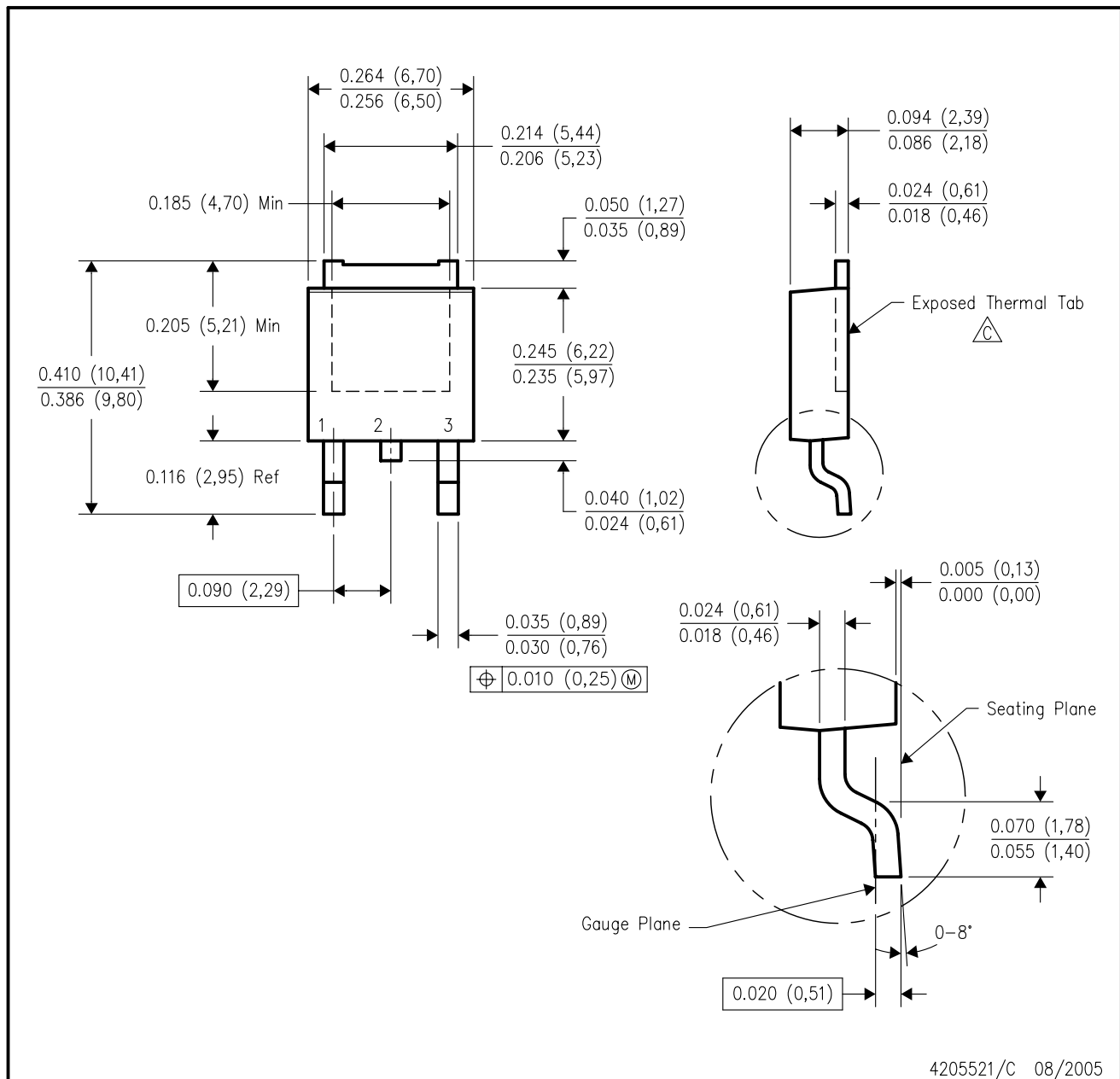
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NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- F. The chamfer is optional.
- G. Thermal pad contour optional within these dimensions.
- H. Falls within JEDEC TO-220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.

KVU (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE

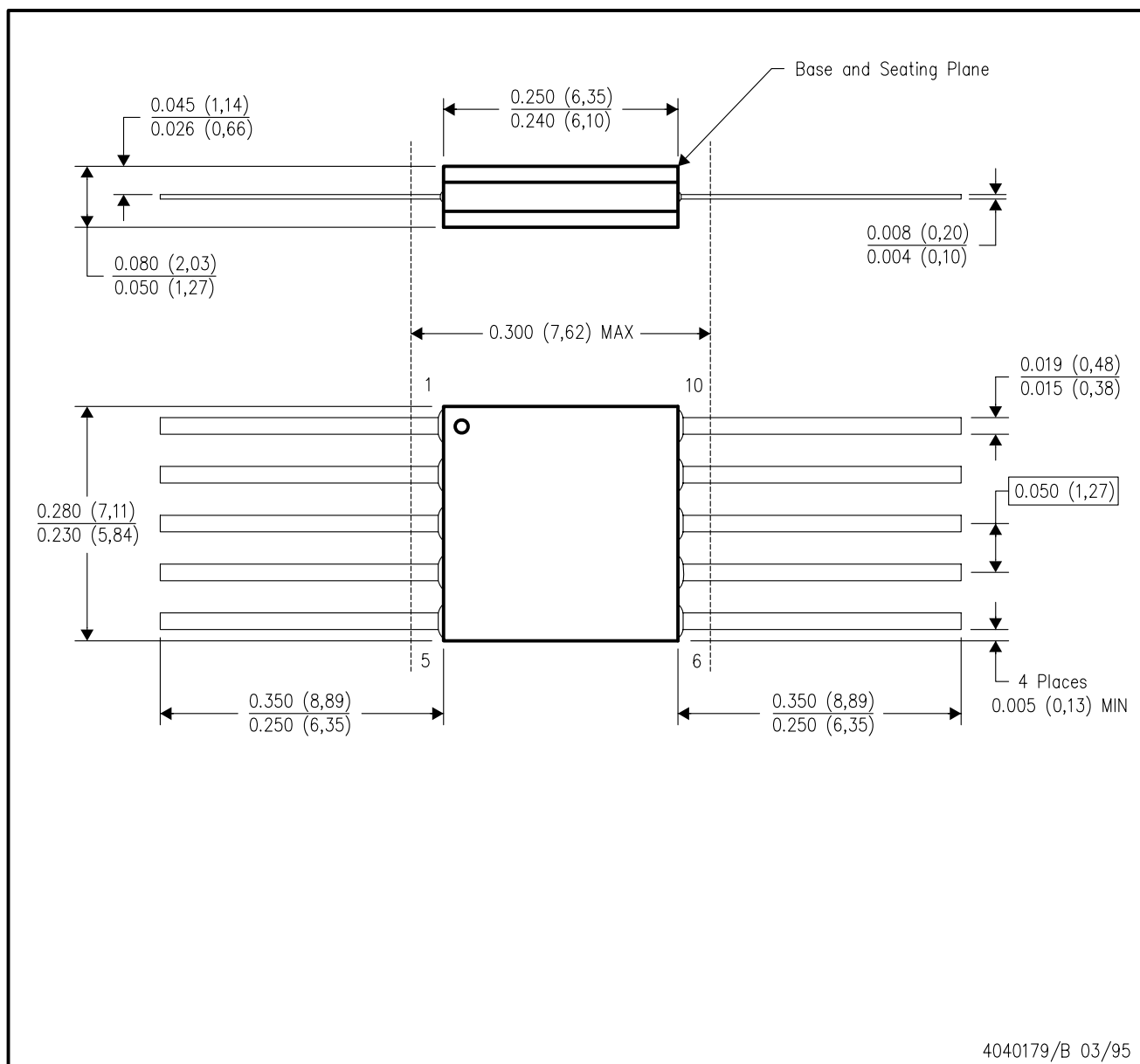


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. The center lead is in electrical contact with the exposed thermal tab.
- D. Body Dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.006 (0,15) per side.
- E. Falls within JEDEC TO-252 variation AA.

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

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